

EMIF06-MSD03F3

6-line low capacitance IPAD™ for micro-SD card with EMI filtering and ESD protection

Features

- EMI low-pass filter
- ESD protection ±15 kV (IEC 61000-4-2)
- Integrated pull up resistors to prevent bus floating when no card is connected
- 208 MHz clock frequency compatible with SDR104 mode (SD3.0)
- Lead-free package
- Coated version option on request
- Electrical card detect option

Benefits

- Low power consumption
- Easy layout thanks to smart pin-out configuration
- Very low PCB space consumption
- High reliability offered by monolithic integration
- Reduction of parasitic elements thanks to CSP integration

Complies with the following standards:

- IEC 61000-4-2 level 4:
 - 15 kV (air discharge)
 - 8 kV (contact discharge)

Application

Micro (T-Flash) secure digital memory card in:

- Mobile phones
- Communication systems

Description

The EMIF06-MSD03F3 is a highly integrated device based on IPAD technology offering two functions: ESD protection to comply with IEC standard, and EMI filtering to reject mobile phone frequencies.

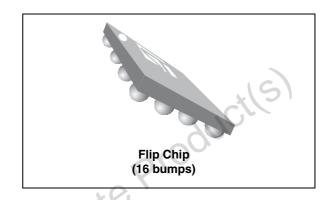
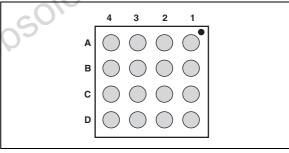


Figure 1. Pin configuration (bump side)



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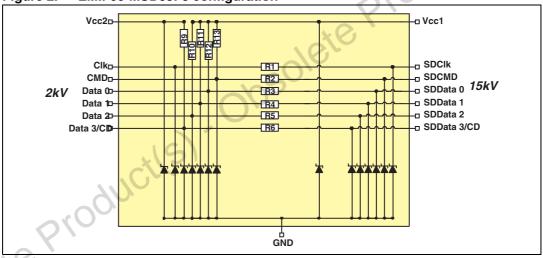
Characteristics EMIF06-MSD03F3

Characteristics 1

Table 1. **Absolute ratings (limiting values)**

Symbol	Parameter	Value	Unit
V _{PP}	ESD discharge IEC 61000-4-2, level 4 air discharge, card side contact discharge, card side air discharge, IC side contact discharge, ICside	15 8 2 2	kV
Tj	Maximum junction temperature	125	°C
T _{op}	Operating temperature range	- 40 to + 85	°C
T _{stg}	Storage temperature range	- 55 to + 150	°C

Figure 2. EMIF06-MSD03F3 configuration



Pin configuration

	Y'		GND		
16	Table 2.	Pin configuration			
1000	Pin	Signal	Pin	Signal	
O/O2	A1	DATA0	C1	CMD	
	A2	DATA1	C2	V _{cc2}	
	А3	SDDATA1	C3	V _{ss}	
	A4	SDDATA0	C4	SDCMD	
	B1	CLK	D1	DATA3/CD	
	B2	V _{cc1}	D2	DATA2	
	В3	V_{SS}	D3	SDDATA2	
	B4	SDCLK	D4	SDDATA3/CD	

EMIF06-MSD03F3 Characteristics

Table 3. Electrical characteristic

Symbol	Parameter	Test conditions		Тур.	Max.	Unit
V_{BR}	Breakdown voltage	I _R = 1 mA	14	16		V
I _{RM}	Leakage current at V _{RM}	V _{RM} = 3 V			0.1	μΑ
R1, R2, R3, R4, R5, R6	Serial resistance	Tolerance ±10 %, matching ±2 %		40		Ω
R9, R10, R11, R12	Pull-up resistance	Tolerance ±10 %, matching ±2 %		50		kΩ
R13	Pull-up resistance on CMD	Tolerance ±10 %		15		kΩ
		V = 0 V, F = 10 MHz, V _{OSC} = 30 mV		10	12	
C _{line}	Data line capacitance	V = 1.8 V, F = 10 MHz, V _{OSC} = 30 mV		7.5	10	pF
		V = 2.9 V, F = 10 MHz, V _{OSC} = 30 mV	2		9	
F ₀	Cut-off frequency	S21 = -3 dB	0	550		MHz
t _R ,t _F	Rise and fall time	C _{load} = 10 pF, low-ref = 0.58 V, high-ref = 1.27 V, V _{DDIO} = 1.8 V		0.98		ns

Figure 3. S21 attenuation measurements Figure 4. Analog crosstalk measurements

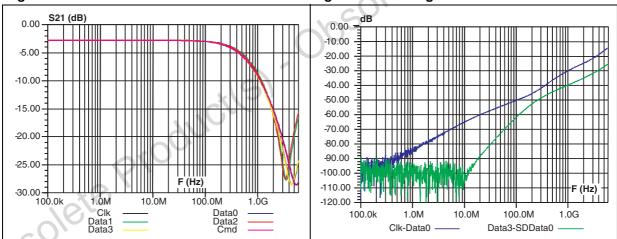
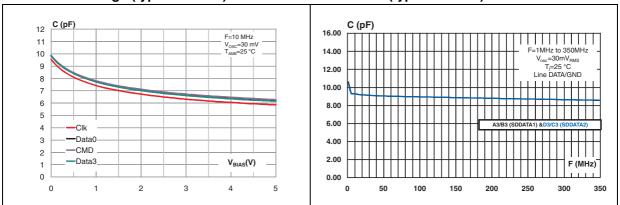


Figure 5. Line capacitance versus applied Figure 6. Line capacitance versus frequency voltage (typical values) (typical values)



Characteristics EMIF06-MSD03F3

Figure 7. Digital crosstalk measurements

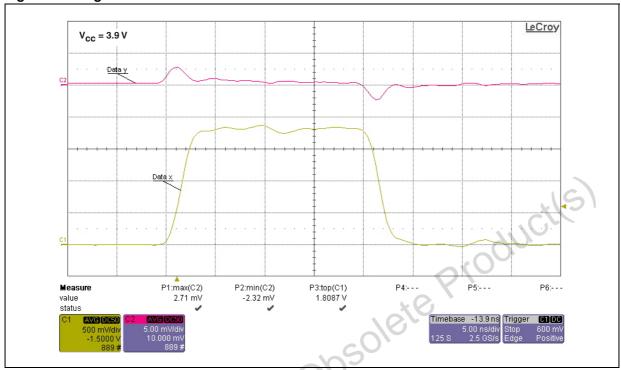
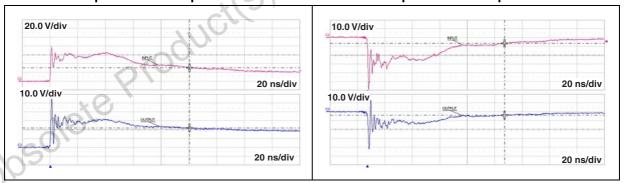


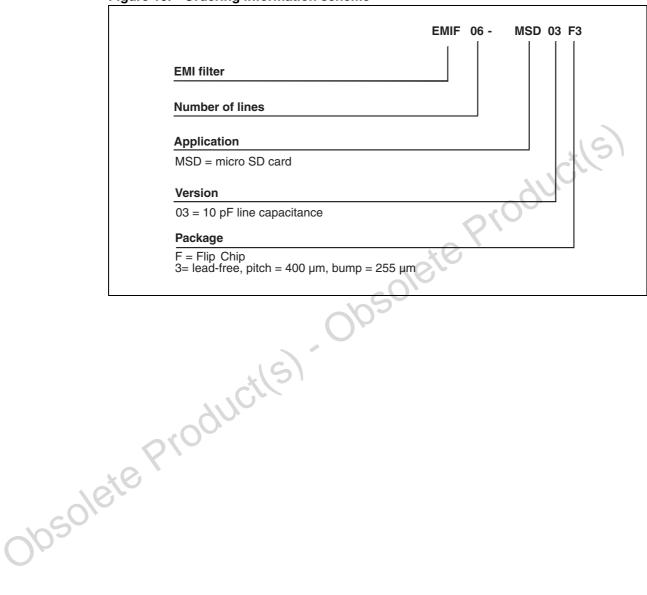
Figure 8. ESD response to IEC 61000-4-2 (+8 kV contact discharge) on one input and one output

Figure 9. ESD response to IEC 61000-4-2 (-8 kV contact discharge) on one input and one output



2 Ordering information scheme

Figure 10. Ordering information scheme



3 Package information

- Epoxy meets UL94, V0
- Lead-free package

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In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

Figure 11. Package dimensions

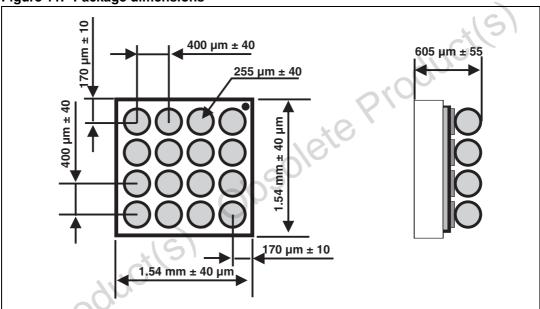


Figure 13. Marking

Copper pad Diameter:
220 µm recommended
260 µm maximum

Solder mask opening:
300 µm minimum

Solder stencil opening:
220 µm recommended

Solder stencil opening:
220 µm recommended

Figure 13. Marking

Dot, ST logo
ECOPACK status

xx = marking
z = manufacturing
location
yww = datecode
y = year,
ww = week

Y W W

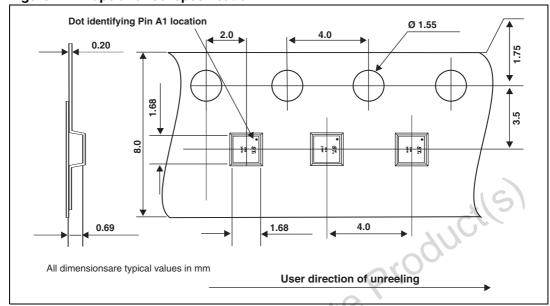


Figure 14. Tape and reel specification

4 Ordering information

Table 4. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
EMIF06-MSD03F3	JV	Flip Chip	3.2 mg	5000	Tape and reel 7"

Note: More information is available in the application notes:

AN2348: "Flip Chip: Package description and recommendations for use"

AN1751: "EMI Filters: Recommendations and measurements"

5 Revision history

Table 5. Document revision history

Date	Revision	Changes
11-Jul-2011	1	First issue.

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